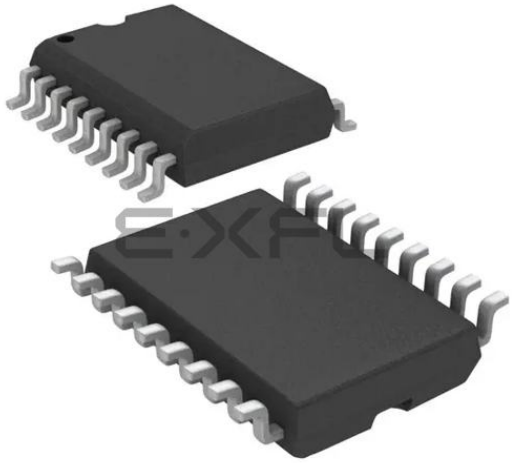

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	12
Program Memory Size	768B (512 x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc54c-04-so

NOTES:

8.0 TIMER0 MODULE AND TMR0 REGISTER

The Timer0 module has the following features:

- 8-bit timer/counter register, TMR0
  - Readable and writable
- 8-bit software programmable prescaler
- Internal or external clock select
  - Edge select for external clock

Figure 8-1 is a simplified block diagram of the Timer0 module, while Figure 8-2 shows the electrical structure of the Timer0 input.

Timer mode is selected by clearing the T0CS bit (OPTION<5>). In Timer mode, the Timer0 module will increment every instruction cycle (without prescaler). If TMR0 register is written, the increment is inhibited for the following two cycles (Figure 8-3 and Figure 8-4). The user can work around this by writing an adjusted value to the TMR0 register.

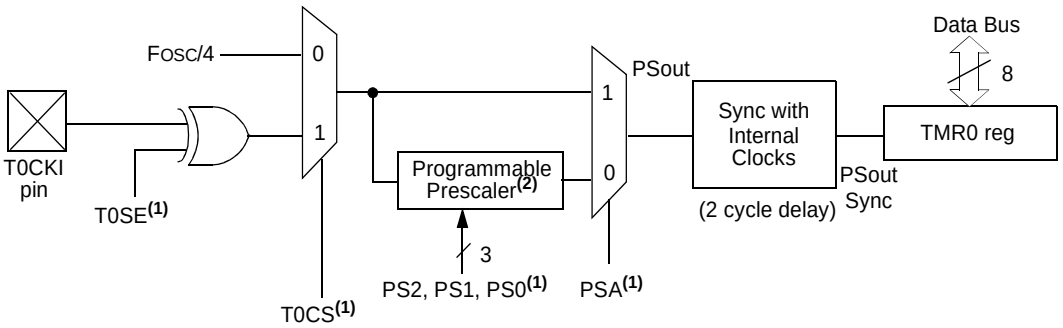
Counter mode is selected by setting the T0CS bit (OPTION<5>). In this mode, Timer0 will increment either on every rising or falling edge of pin T0CKI. The incrementing edge is determined by the source edge select bit T0SE (OPTION<4>). Clearing the T0SE bit selects the rising edge. Restrictions on the external clock input are discussed in detail in Section 8.1.

Note:	The prescaler may be used by either the Timer0 module or the Watchdog Timer, but not both.

The prescaler assignment is controlled in software by the control bit PSA (OPTION<3>). Clearing the PSA bit will assign the prescaler to Timer0. The prescaler is not readable or writable. When the prescaler is assigned to the Timer0 module, prescale values of 1:2, 1:4,..., 1:256 are selectable. Section 8.2 details the operation of the prescaler.

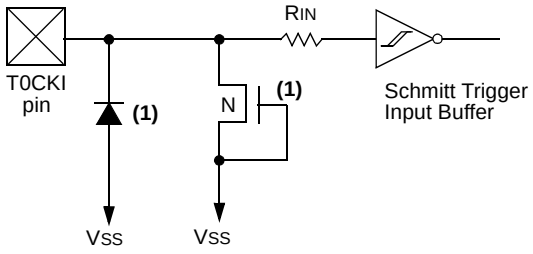
A summary of registers associated with the Timer0 module is found in Table 8-1.

FIGURE 8-1: TIMER0 BLOCK DIAGRAM



Note 1: Bits T0CS, T0SE, PSA, PS2, PS1 and PS0 are located in the OPTION register (Section 6.4).
2: The prescaler is shared with the Watchdog Timer (Figure 8-6).

FIGURE 8-2: ELECTRICAL STRUCTURE OF T0CKI PIN



Note 1: ESD protection circuits.

8.1 Using Timer0 with an External Clock

When an external clock input is used for Timer0, it must meet certain requirements. The external clock requirement is due to internal phase clock (TOSC) synchronization. Also, there is a delay in the actual incrementing of Timer0 after synchronization.

8.1.1 EXTERNAL CLOCK SYNCHRONIZATION

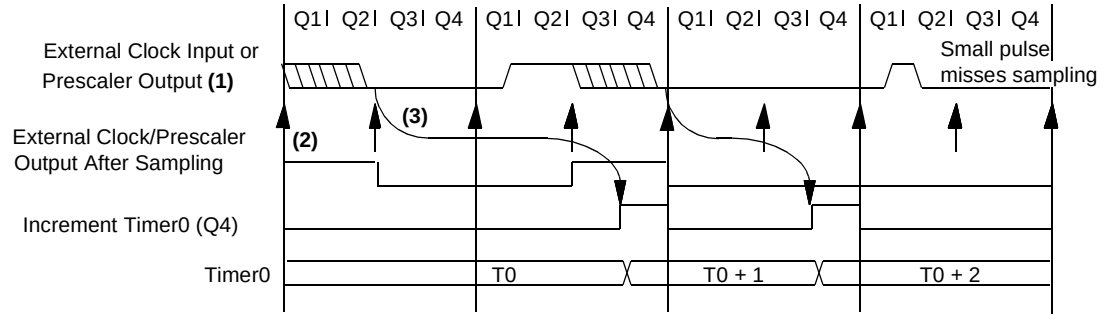
When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 8-5). Therefore, it is necessary for T0CKI to be high for at least 2TOSC (and a small RC delay of 20 ns) and low for at least 2TOSC (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

When a prescaler is used, the external clock input is divided by the asynchronous ripple counter-type prescaler so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple counter must be taken into account. Therefore, it is necessary for T0CKI to have a period of at least 4TOSC (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T0CKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

8.1.2 TIMER0 INCREMENT DELAY

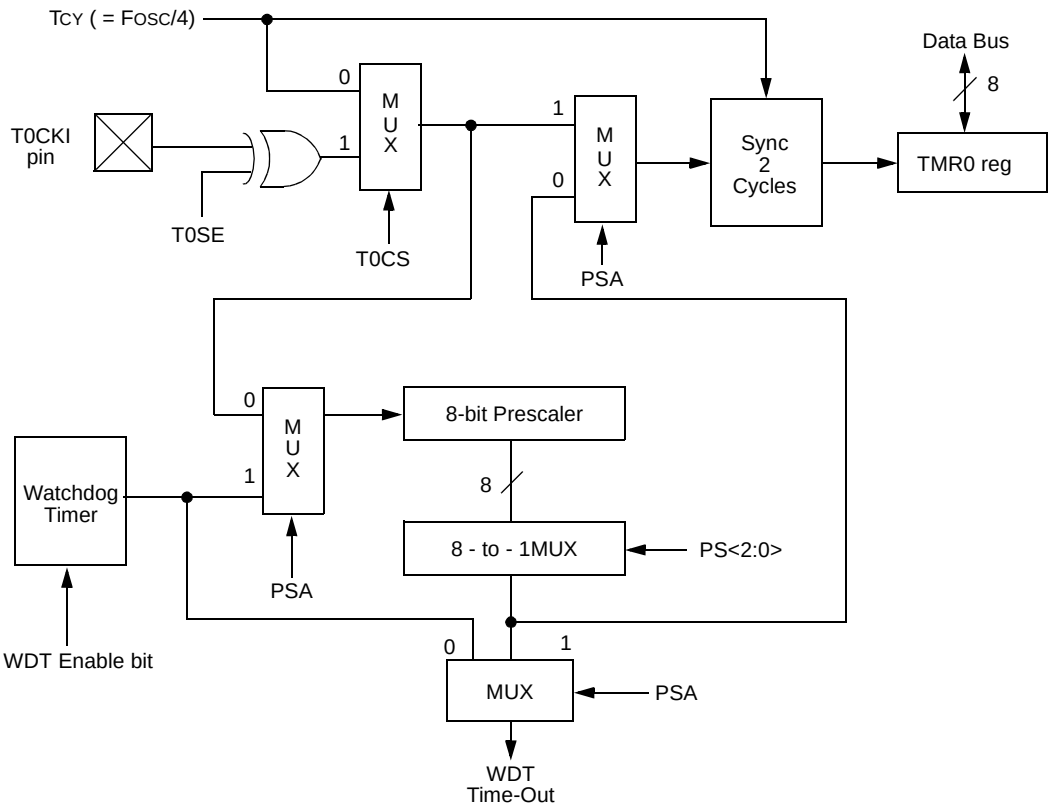
Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the Timer0 module is actually incremented. Figure 8-5 shows the delay from the external clock edge to the timer incrementing.

FIGURE 8-5: TIMER0 TIMING WITH EXTERNAL CLOCK



Note 1: External clock if no prescaler selected, prescaler output otherwise.
2: The arrows indicate the points in time where sampling occurs.
3: Delay from clock input change to Timer0 increment is 3Tosc to 7Tosc (duration of Q = Tosc). Therefore, the error in measuring the interval between two edges on Timer0 input = ± 4Tosc max.

FIGURE 8-6: BLOCK DIAGRAM OF THE TIMER0/WDT PRESCALER



Note: T0CS, T0SE, PSA, PS<2:0> are bits in the OPTION register.

NOTES:

10.0 INSTRUCTION SET SUMMARY

Each PIC16C5X instruction is a 12-bit word divided into an OPCODE, which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16C5X instruction set summary in Table 10-2 groups the instructions into byte-oriented, bit-oriented, and literal and control operations. Table 10-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator is used to specify which one of the 32 file registers in that bank is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an 8 or 9-bit constant or literal value.

TABLE 10-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x1F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1) The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0 (store result in W) d = 1 (store result in file register 'f') Default is d = 1
label	Label name
TOS	Top of Stack
PC	Program Counter
WDT	Watchdog Timer Counter
$\overline{TO}$	Time-out bit
$\overline{PD}$	Power-down bit
dest	Destination, either the W register or the specified register file location
[ ]	Options
( )	Contents
→	Assigned to
< >	Register bit field
∈	In the set of
italics	User defined term (font is courier)

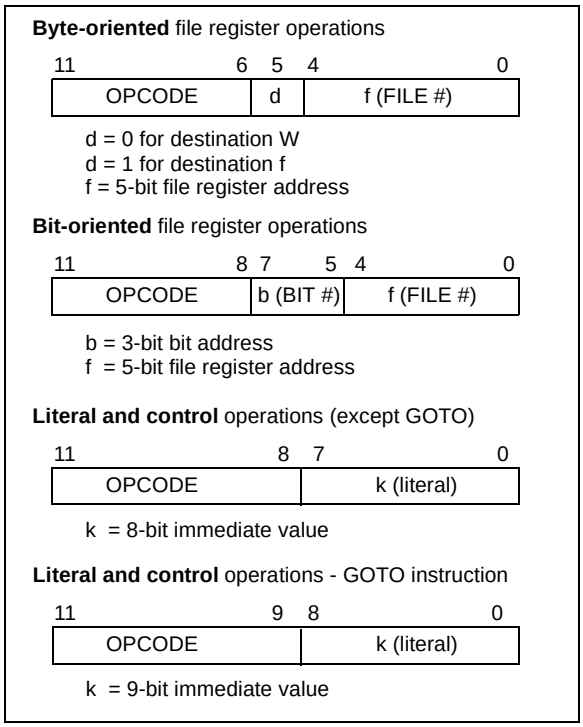
All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time would be 1 μs. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time would be 2 μs.

Figure 10-1 shows the three general formats that the instructions can have. All examples in the figure use the following format to represent a hexadecimal number:

0xhhh

where 'h' signifies a hexadecimal digit.

FIGURE 10-1: GENERAL FORMAT FOR INSTRUCTIONS



BSF **Bit Set f**

Syntax: [*label*] BSF f,b

Operands: $0 \le f \le 31$
$0 \le b \le 7$

Operation: $1 \rightarrow (f<b>)$

Status Affected: None

Encoding:

0101	bbbf	ffff

Description: Bit 'b' in register 'f' is set.

Words: 1

Cycles: 1

Example:
```
BSF     FLAG_REG,    7
```
Before Instruction
FLAG_REG = 0x0A
After Instruction
FLAG_REG = 0x8A

BTFSC **Bit Test f, Skip if Clear**

Syntax: [*label*] BTFSC f,b

Operands: $0 \le f \le 31$
$0 \le b \le 7$

Operation: skip if (f<b>) = 0

Status Affected: None

Encoding:

0110	bbbf	ffff

Description: If bit 'b' in register 'f' is 0 then the next instruction is skipped.
If bit 'b' is 0 then the next instruction fetched during the current instruction execution is discarded, and a `NOP` is executed instead, making this a 2-cycle instruction.

Words: 1

Cycles: 1(2)

Example:
```
HERE    BTFSC   FLAG,1
FALSE   GOTO    PROCESS_CODE
TRUE    •
        •
        •
```
Before Instruction
PC = address `(HERE)`
After Instruction
if FLAG<1> = 0,
PC = address `(TRUE)`;
if FLAG<1> = 1,
PC = address `(FALSE)`

BTFSS **Bit Test f, Skip if Set**

Syntax: [*label*] BTFSS f,b

Operands: $0 \le f \le 31$
$0 \le b < 7$

Operation: skip if (f<b>) = 1

Status Affected: None

Encoding:

0111	bbbf	ffff

Description: If bit 'b' in register 'f' is '1' then the next instruction is skipped.
If bit 'b' is '1', then the next instruction fetched during the current instruction execution, is discarded and a `NOP` is executed instead, making this a 2-cycle instruction.

Words: 1

Cycles: 1(2)

Example:
```
HERE    BTFSS   FLAG,1
FALSE   GOTO    PROCESS_CODE
TRUE    •
        •
        •
```
Before Instruction
PC = address `(HERE)`
After Instruction
If FLAG<1> = 0,
PC = address `(FALSE)`;
if FLAG<1> = 1,
PC = address `(TRUE)`

XORLW **Exclusive OR literal with W**

Syntax: [*label*] XORLW k

Operands: $0 \le k \le 255$

Operation: (W) .XOR. k → (W)

Status Affected: Z

Encoding:

1111	kkkk	kkkk

Description: The contents of the W register are XOR'ed with the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Example:
```
XORLW  0xAF
```
Before Instruction
W = 0xB5
After Instruction
W = 0x1A

XORWF **Exclusive OR W with f**

Syntax: [*label*] XORWF f,d

Operands: $0 \le f \le 31$
$d \in [0,1]$

Operation: (W) .XOR. (f) → (dest)

Status Affected: Z

Encoding:

0001	10df	ffff

Description: Exclusive OR the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example
```
XORWF  REG,1
```
Before Instruction
REG = 0xAF
W = 0xB5
After Instruction
REG = 0x1A
W = 0xB5

13.2 DC Characteristics: PIC16CR54A-04E, 10E, 20E (Extended)

PIC16CR54A-04E, 10E, 20E (Extended)			Standard Operating Conditions (unless otherwise specified) Operating Temperature –40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	**Supply Voltage** RC, XT and LP modes HS mode	 3.25 4.5	 — —	 6.0 5.5	 V V	
D002	VDR	**RAM Data Retention Voltage**(1)	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	**VDD Start Voltage** to ensure Power-on Reset	—	VSS	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	**VDD Rise Rate** to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
D010	IDD	**Supply Current**(2) RC(3) and XT modes HS mode HS mode	 — — —	 1.8 4.8 9.0	 3.3 10 20	 mA mA mA	 FOSC = 4.0 MHz, VDD = 5.5V FOSC = 10 MHz, VDD = 5.5V FOSC = 16 MHz, VDD = 5.5V
D020	IPD	**Power-down Current**(2)	— —	5.0 0.8	22 18	µA µA	VDD = 3.25V, WDT enabled VDD = 3.25V, WDT disabled

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode.The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

FIGURE 14-9: VTH (INPUT THRESHOLD VOLTAGE) OF I/O PINS vs. VDD

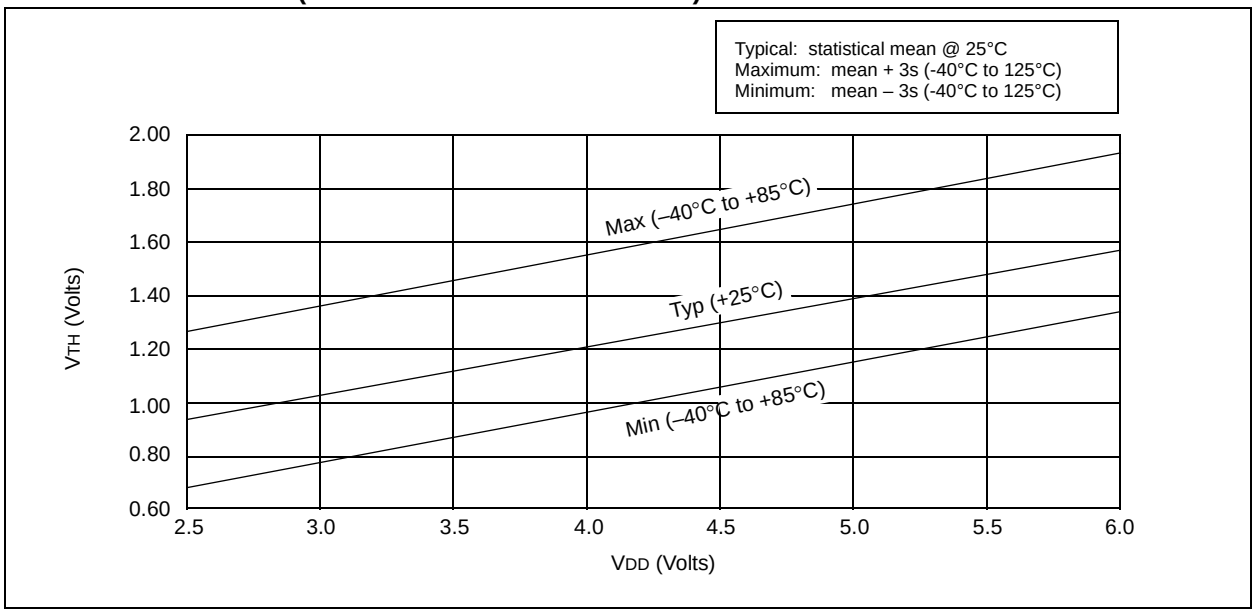
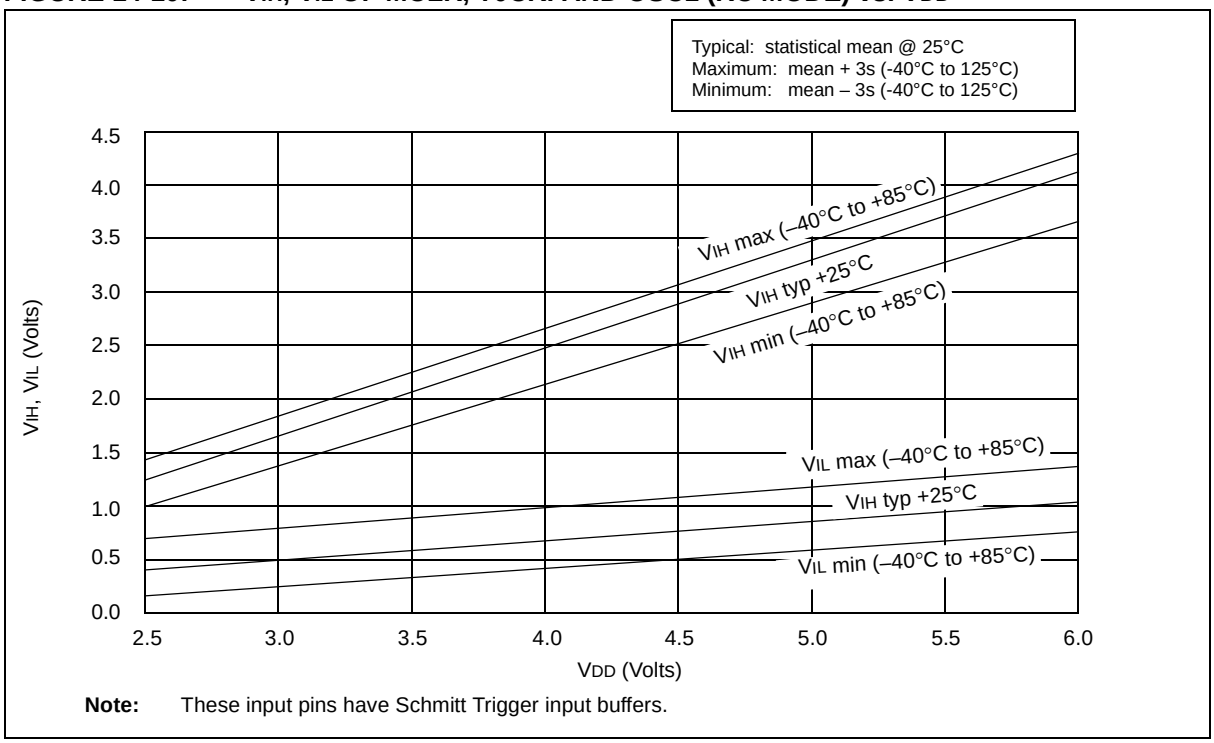


FIGURE 14-10: VIH, VIL OF $\overline{\text{MCLR}}$, T0CKI AND OSC1 (RC MODE) vs. VDD



Note: These input pins have Schmitt Trigger input buffers.

FIGURE 16-14: TYPICAL IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 300 pF, 25°C)

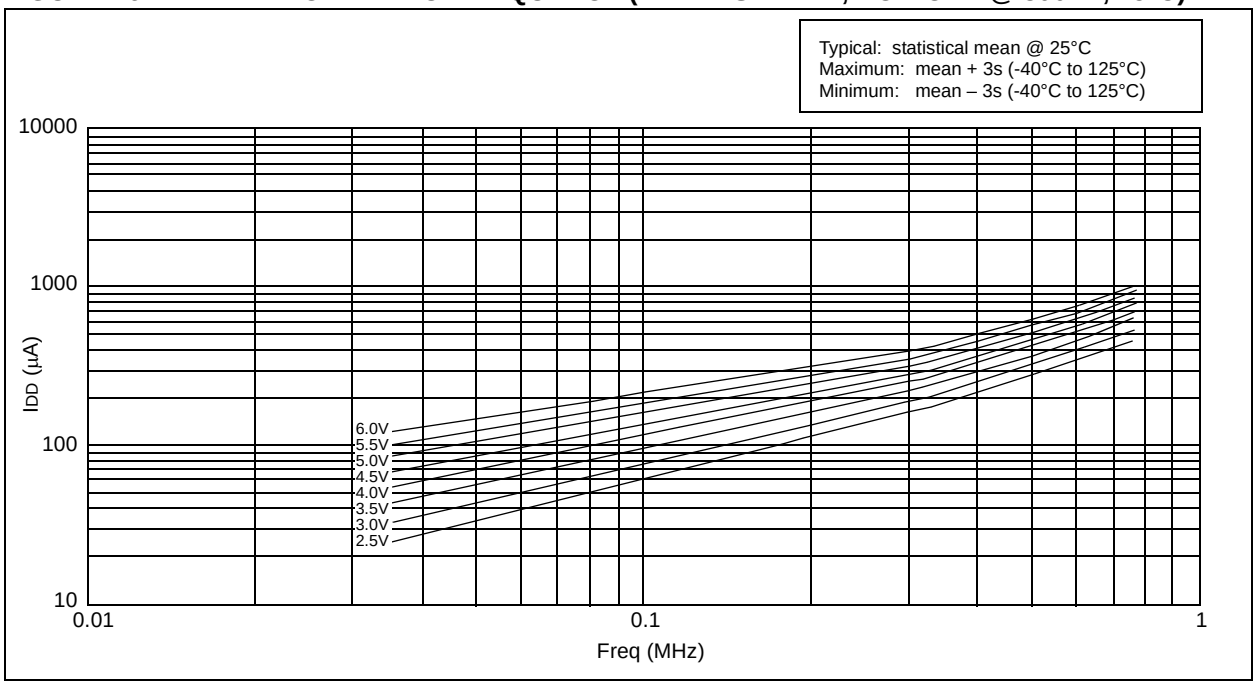
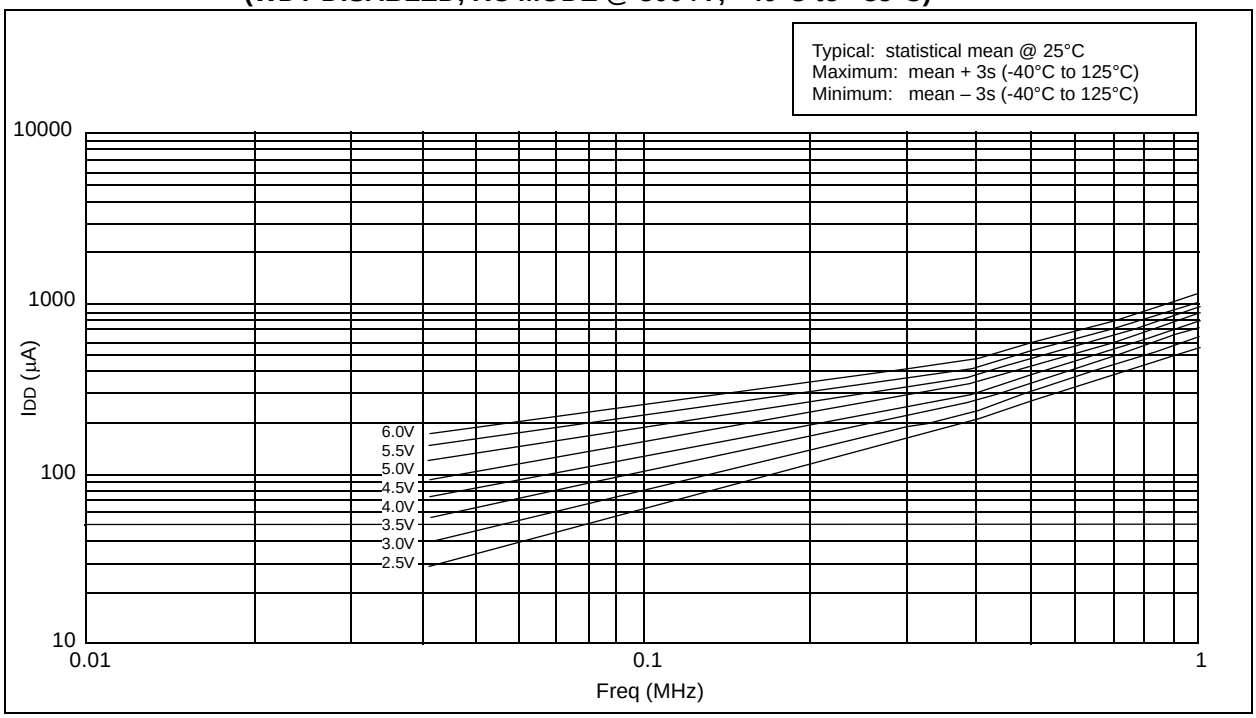


FIGURE 16-15: MAXIMUM IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 300 pF, –40°C to +85°C)



17.1 DC Characteristics: PIC16C54C/C55A/C56A/C57C/C58B-04, 20 (Commercial, Industrial)
PIC16LC54C/LC55A/LC56A/LC57C/LC58B-04 (Commercial, Industrial)
PIC16CR54C/CR56A/CR57C/CR58B-04, 20 (Commercial, Industrial)
PIC16LCR54C/LCR56A/LCR57C/LCR58B-04 (Commercial, Industrial)

PIC16LC5X **PIC16LCR5X** (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
PIC16C5X **PIC16CR5X** (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise specified)** Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Symbol**	**Characteristic/Device**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	IDD	**Supply Current(2,3)**					
D010		PIC16LC5X	—	0.5	2.4	mA	FOSC = 4.0 MHz, VDD = 5.5V, XT and RC modes
			—	11	27	µA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Commercial
			—	14	35	µA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Industrial
D010A		PIC16C5X	—	1.8	2.4	mA	FOSC = 4 MHz, VDD = 5.5V, XT and RC modes
			—	2.6	3.6*	mA	
			—	4.5	16	mA	FOSC = 10 MHz, VDD = 3.0V, HS mode
			—	14	32	µA	FOSC = 20 MHz, VDD = 5.5V, HS mode
			—	17	40	µA	FOSC = 32 kHz, VDD = 3.0V, LP mode, Commercial
							FOSC = 32 kHz, VDD = 3.0V, LP mode, Industrial

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

17.5 Timing Diagrams and Specifications

FIGURE 17-6: EXTERNAL CLOCK TIMING - PIC16C5X, PIC16CR5X

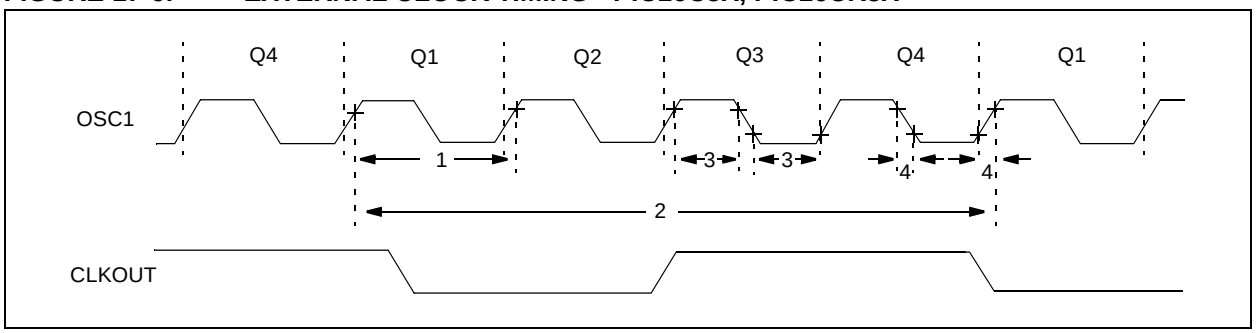


TABLE 17-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C5X, PIC16CR5X

AC Characteristics	Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial –40°C ≤ TA ≤ +125°C for extended						
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	FOSC	External CLKIN Frequency(1)	DC	—	4.0	MHz	XT OSC mode
			DC	—	4.0	MHz	HS OSC mode (04)
			DC	—	20	MHz	HS OSC mode (20)
			DC	—	200	kHz	LP OSC mode
		Oscillator Frequency(1)	DC	—	4.0	MHz	RC OSC mode
			0.45	—	4.0	MHz	XT OSC mode
			4.0	—	4.0	MHz	HS OSC mode (04)
			4.0	—	20	MHz	HS OSC mode (20)
			5.0	—	200	kHz	LP OSC mode
1	TOSC	External CLKIN Period(1)	250	—	—	ns	XT OSC mode
			250	—	—	ns	HS OSC mode (04)
			50	—	—	ns	HS OSC mode (20)
			5.0	—	—	µs	LP OSC mode
		Oscillator Period(1)	250	—	—	ns	RC OSC mode
			250	—	2,200	ns	XT OSC mode
			250	—	250	ns	HS OSC mode (04)
			50	—	250	ns	HS OSC mode (20)
			5.0	—	200	µs	LP OSC mode

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.
When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Instruction cycle period (TCY) equals four times the input oscillator time base period.

FIGURE 18-6: TYPICAL IPD vs. VDD, WATCHDOG ENABLED (25°C)

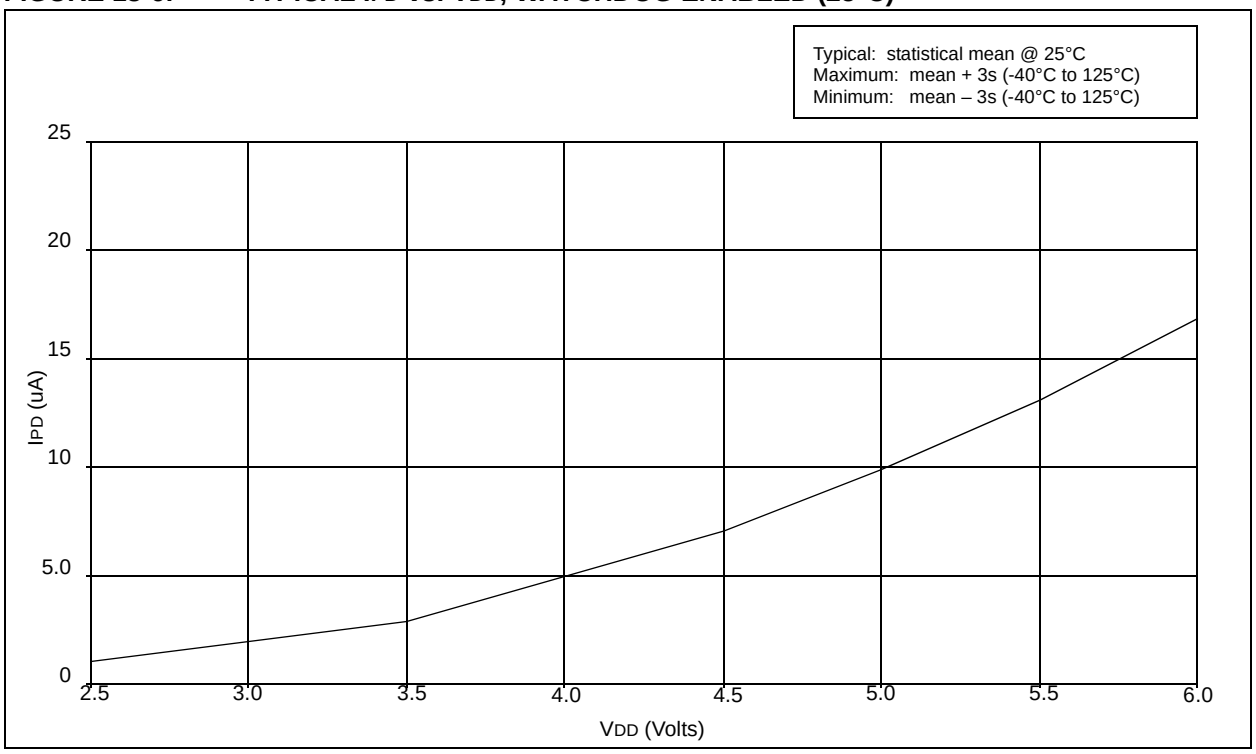


FIGURE 18-7: TYPICAL IPD vs. VDD, WATCHDOG ENABLED (–40°C, 85°C)

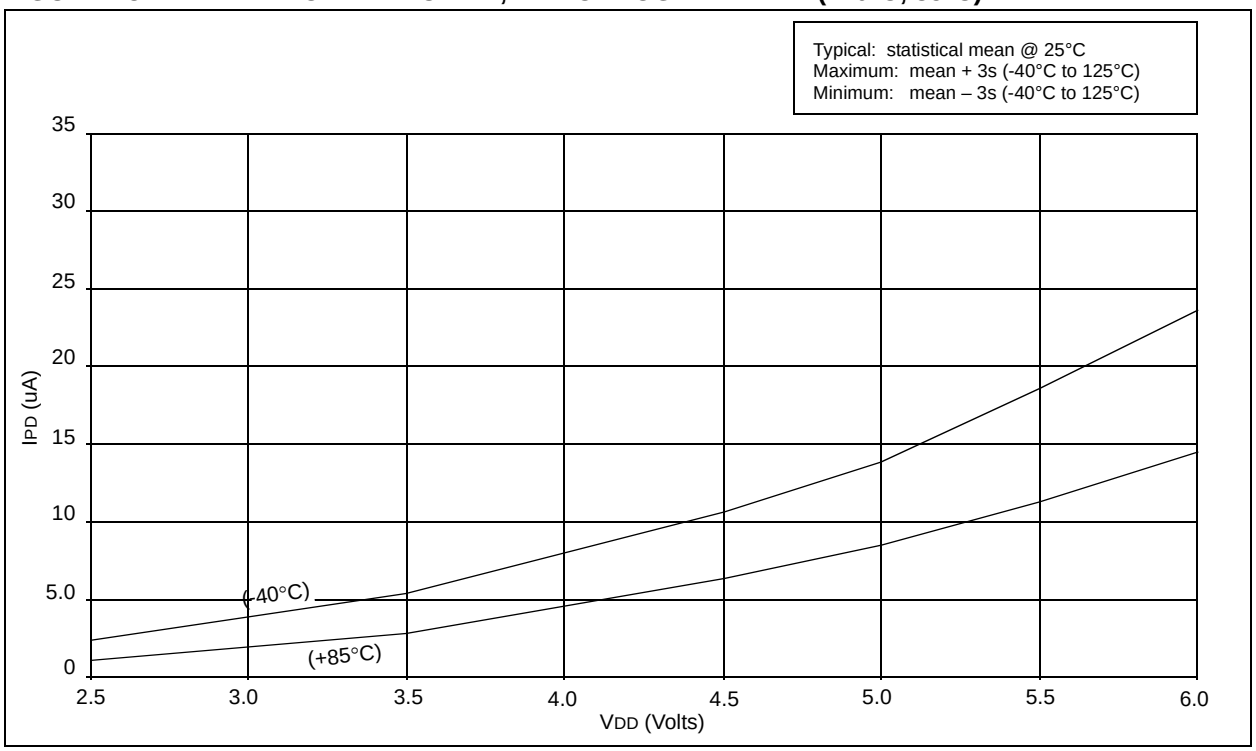


FIGURE 18-12: TYPICAL IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 100 pF, 25°C)

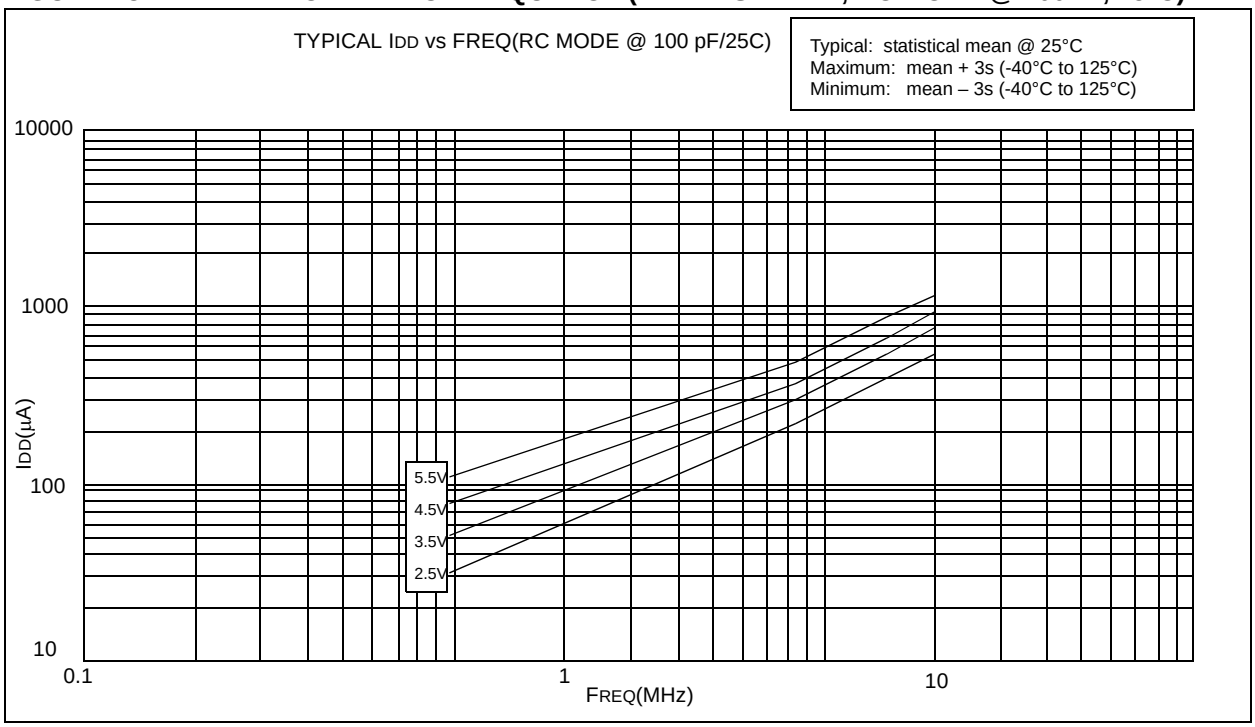
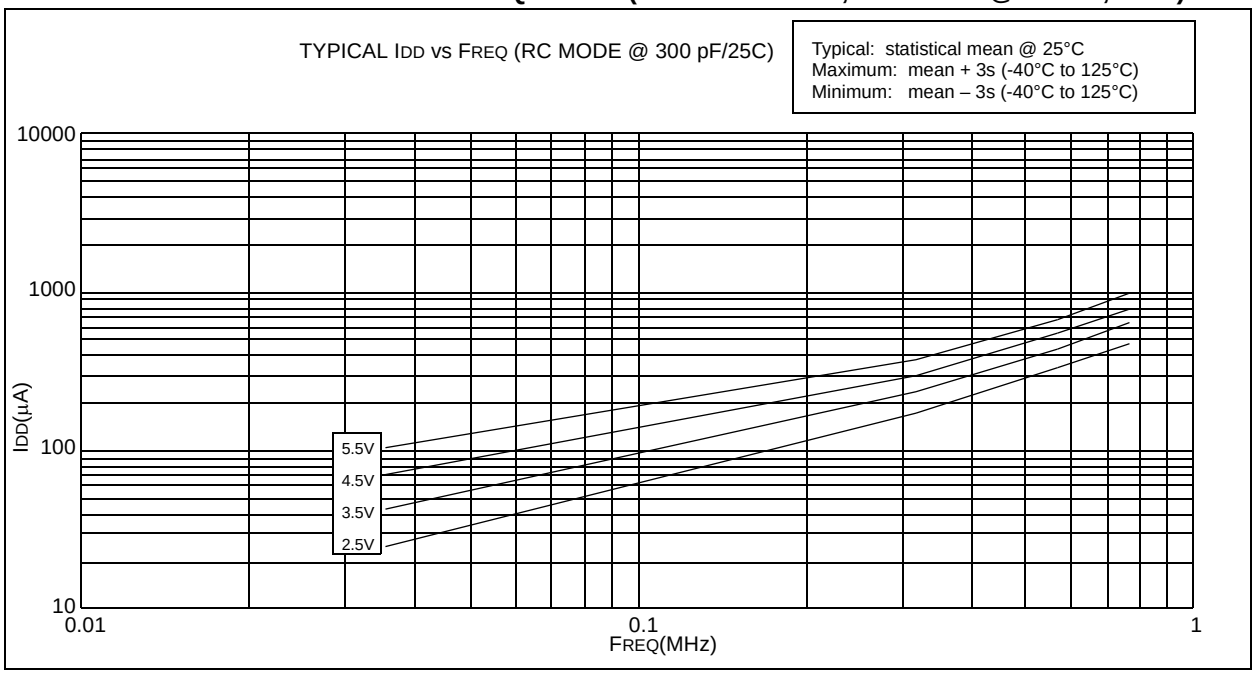


FIGURE 18-13: TYPICAL IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 300 pF, 25°C)



20.0 DEVICE CHARACTERIZATION - PIC16LC54C 40MHz

The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

"Typical" represents the mean of the distribution at 25°C. "Maximum" or "minimum" represents (mean + 3σ) or (mean – 3σ) respectively, where σ is a standard deviation, over the whole temperature range.

FIGURE 20-1: TYPICAL IPD vs. VDD, WATCHDOG DISABLED (25°C)

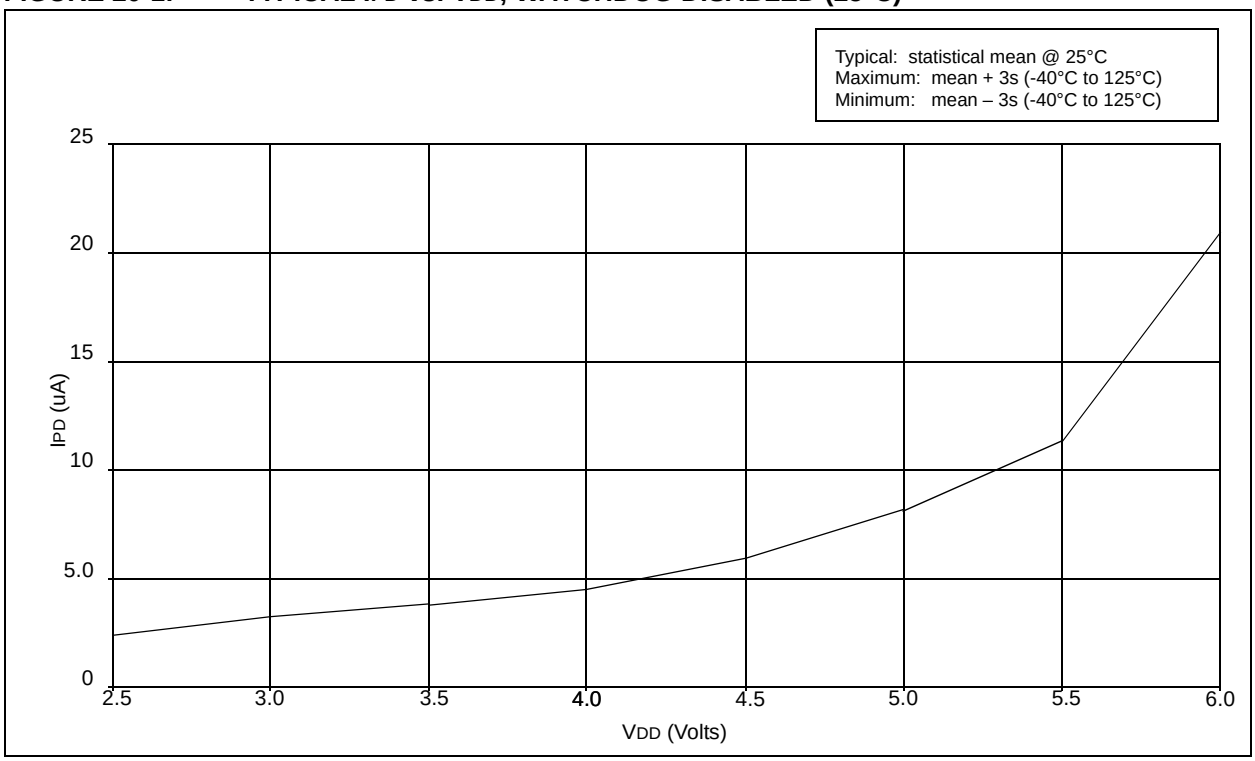
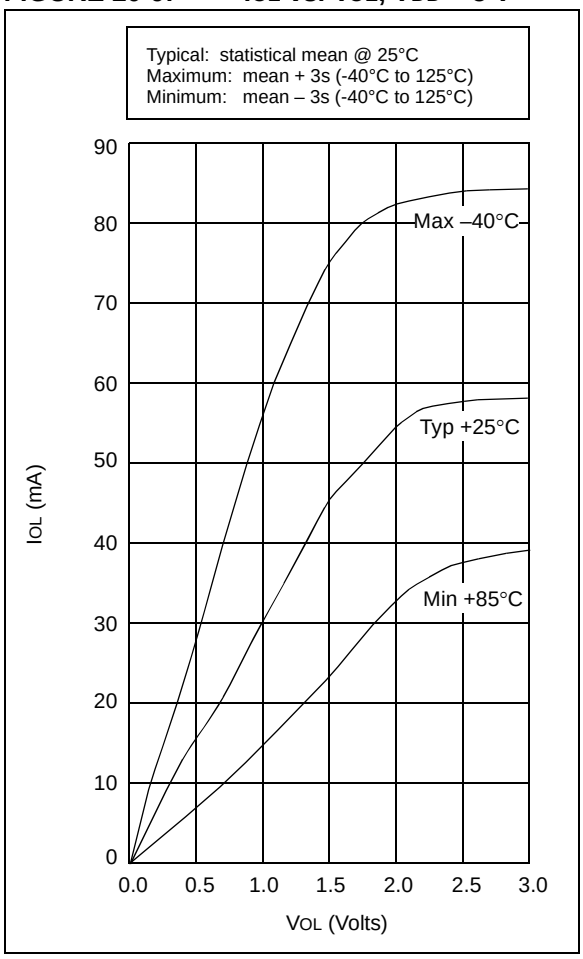
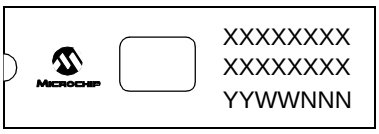


FIGURE 20-9: I_{OL} vs. V_{OL}, V_{DD} = 5 V

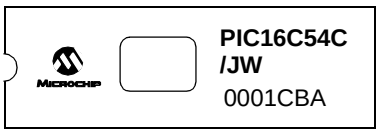


Package Marking Information (Cont'd)

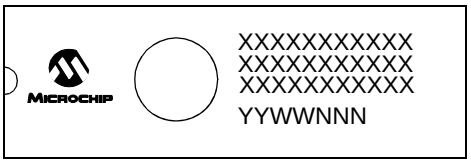
18-Lead CERDIP Windowed



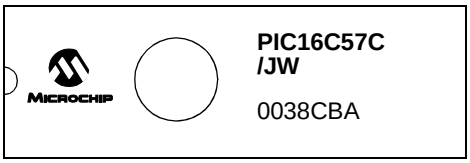
Example



28-Lead CERDIP Windowed



Example

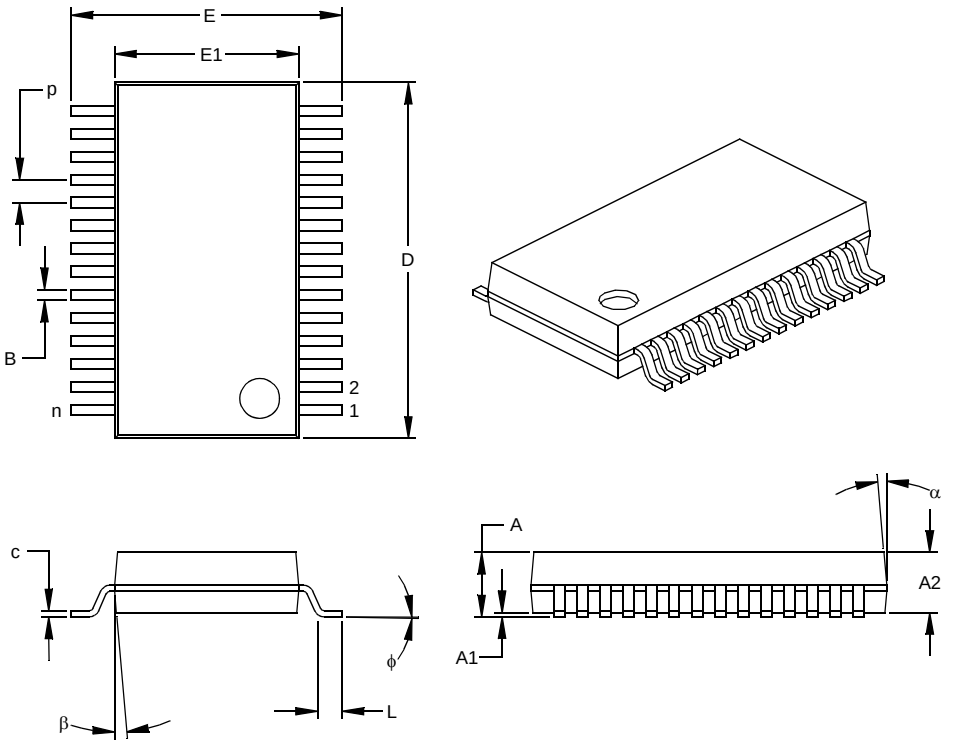


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

28-Lead Plastic Shrink Small Outline (SS) – 209 mil, 5.30 mm (SSOP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	p		.026			0.65	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.319	7.59	7.85	8.10
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.396	.402	.407	10.06	10.20	10.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	c	.004	.007	.010	0.10	0.18	0.25
Foot Angle	ϕ	0	4	8	0.00	101.60	203.20
Lead Width	B	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-150
Drawing No. C04-073

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	-	XX	X	/XX	XXX
Device		Frequency Range/OSC Type	Temperature Range	Package	Pattern

Device	PIC16C54	PIC16C54T(2)
	PIC16C54A	PIC16C54AT(2)
	PIC16CR54A	PIC16CR54AT(2)
	PIC16C54C	PIC16C54CT(2)
	PIC16CR54C	PIC16CR54CT(2)
	PIC16C55	PIC16C55T(2)
	PIC16C55A	PIC16C55AT(2)
	PIC16C56	PIC16C56T(2)
	PIC16C56A	PIC16C56AT(2)
	PIC16CR56A	PIC16CR56AT(2)
	PIC16C57	PIC16C57T(2)
	PIC16C57C	PIC16C57CT(2)
	PIC16CR57C	PIC16CR57CT(2)
	PIC16C58B	PIC16C58BT(2)
	PIC16CR58B	PIC16CR58BT(2)

Frequency Range/ Oscillator Type	RC	Resistor Capacitor
	LP	Low Power Crystal
	XT	Standard Crystal/Resonator
	HS	High Speed Crystal
	02	200 KHz (LP) or 2 MHz (XT and RC)
	04	200 KHz (LP) or 4 MHz (XT and RC)
	10	10 MHz (HS only)
	20	20 MHz (HS only)
	40	40 MHz (HS only)
	b(4)	No oscillator type for JW packages(3)

*RC/LP/XT/HS are for 16C54/55/56/57 devices only
-02 is available for 16LV54A only
-04/10/20 options are available for all other devices
-40 is available for 16C54C/55A/56A/57C/58B devices only

Temperature Range	b(4)	=	0°C to +70°C
	I	=	-40°C to +85°C
	E	=	-40°C to +125°C

Package	S	=	Die in Waffle Pack
	JW	=	28-pin 600 mil/18-pin 300 mil windowed CERDIP(3)
	P	=	28-pin 600 mil/18-pin 300 mil PDIP
	SO	=	300 mil SOIC
	SS	=	209 mil SSOP
	SP	=	28-pin 300 mil Skinny PDIP

*See Section 21 for additional package information.

Pattern	QTP, SQTP, ROM code (factory specified) or Special Requirements. Blank for OTP and Windowed devices.

Examples:

a) PIC16C55A - 04/P 301 = Commercial Temp., PDIP package, 4 MHz, standard VDD limits, QTP pattern #301

b) PIC16LC54C - 04I/SO Industrial Temp., SOIC package, 200 kHz, extended VDD limits

c) PIC16C57 - RC/SP = RC Oscillator, commercial temp, skinny PDIP package, 4 MHz, standard VDD limits

d) PIC16C58BT -40/SS 123 = commercial temp, SSOP package in tape and reel, 4 MHz, extended VDD limits, ROM pattern #123

Note 1: C = normal voltage range
LC = extended

2: T = in tape and reel - SOIC and SSOP packages only

3: JW Devices are UV erasable and can be programmed to any device configuration. JW Devices meet the electrical requirements of each oscillator type, including LC devices.

4: b = Blank

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Worldwide Site (www.microchip.com)